

# [MULTI-CHIP PACKAGE]

## Abstract

A multi-chip package structure is provided. The multi-chip package comprises a first chip, a second chip, a plurality of bumps and a plurality of contacts. The first chip has an active surface. The second chip is mounted on the active surface of the first chip and the height of the second chip in a direction perpendicular to the active surface of the first chip is defined as  $h_1$ . The bumps are positioned between the active surface of the first chip and the second chip and the height of the bumps in a direction perpendicular to the active surface of the first chip is defined as  $h_2$ . The contacts protrude from the active surface of the first chip and the height of the contacts in a direction perpendicular to the active surface of the first chip is defined as  $h_3$ . The values of  $h_1$ ,  $h_2$  and  $h_3$  are related by the inequality:  $h_3 \geq h_1 + h_2$ .